



EGF30A THRU EGF30M

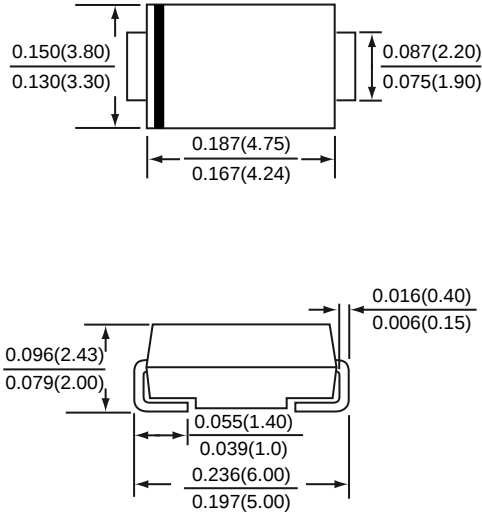
SURFACE MOUNT GLASS PASSIVATED JUNCTION HIGH EFFICIENT RECTIFIER

Reverse Voltage - 50 to 1000 Volts

Forward Current - 3.0 Amperes

PATENTED

SMB/DO-214AA



*Dimensions in inches and (millimeters)

SUPEREX IITM



FEATURES

- * GPRC (Glass Passivated Rectifier Chip) inside
- * Glass passivated cavity-free junction
- * Ideal for surface mount automotive applications
- * Superfast recovery time for high efficiency
- * Built-in strain relief
- * Easy pick and place
- * High temperature soldering guaranteed: 260°C/10 seconds, at terminals
- * Plastic package has Underwriters Laboratory Flammability Classification 94V-0

MECHANICAL DATA

Case : JEDEC DO-214AA molded plastic over passivated chip

Terminals : Tin plated, solderable per MIL-STD-750, Method 2026

Polarity : Color band denotes cathode end

Weight : 0.004 ounces , 0.12 gram

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified.	SYMBOLS	EGF30							UNITS
		A	B	D	G	J	K	M	
Maximum repetitive peak reverse voltage	VRRM	50	100	200	400	600	800	1000	Volts
Maximum RMS voltage	VRMS	35	70	140	280	420	560	700	Volts
Maximum DC blocking voltage	VDC	50	100	200	400	600	800	1000	Volts
Maximum average forward rectified current (SEE FIG.1)	I (AV)	3.0							Amps
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	IFSM	115				105			Amps
Maximum instantaneous forward voltage at 3.0 A	VF	1.0			1.25		1.7		Volts
Maximum DC reverse current TA=25°C TA=125°C at rated DC blocking voltage TA=150°C	IR	5 50 120				5 120 -			uA
Maximum reverse recovery time (NOTE 1)	trr	50				75			nS
Typical junction capacitance (NOTE 2)	CJ	75							pF
Typical thermal resistance (NOTE 3)	RθJA RθJL	47 12							°C / W
Operating junction and storage temperature range	TJ,TSTG	-65 to +175							°C

NOTES : (1) Reverse recovery test condition : IF 0.5A, IR=1.0A, Irr=0.25A

(2) Measured at 1.0 MHz and applied reverse voltage of 4.0 Volts

(3) Thermal resistance from junction to ambient and from junction to lead P.C.B. mounted on 0.2 x 0.2" (5.0 x 5.0mm) copper pad areas.

RATINGS AND CHARACTERISTIC CURVES EGF30A THRU EGF30M

FIG.1 - FORWARD CURRENT DERATING CURVE

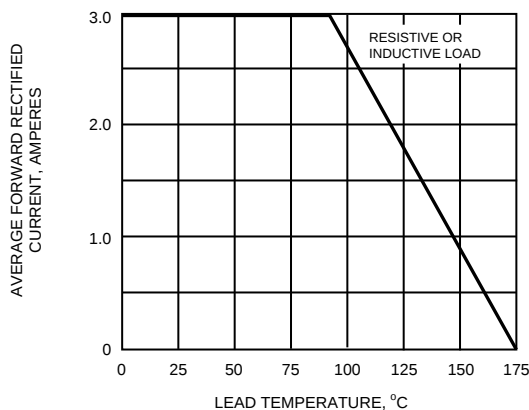


FIG.2 - MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

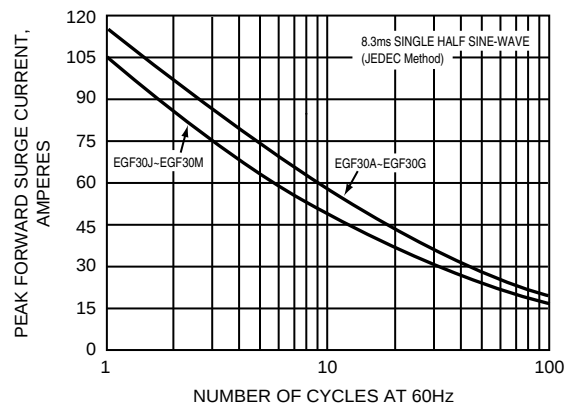


FIG.3 - TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

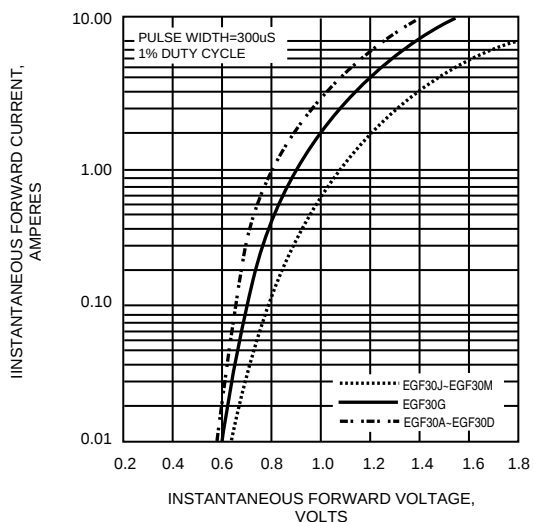


FIG.4 - TYPICAL REVERSE CHARACTERISTICS

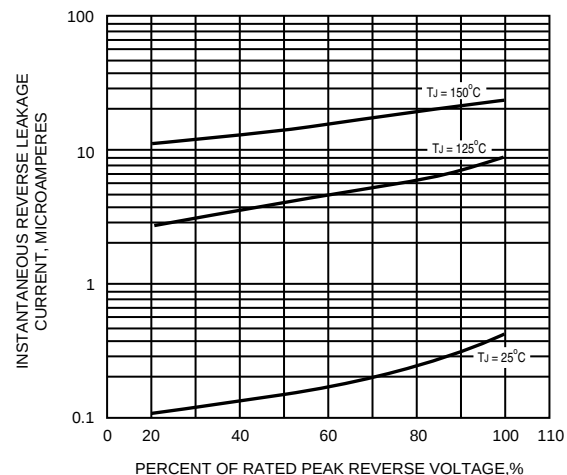


FIG.5 - TYPICAL JUNCTION CAPACITANCE

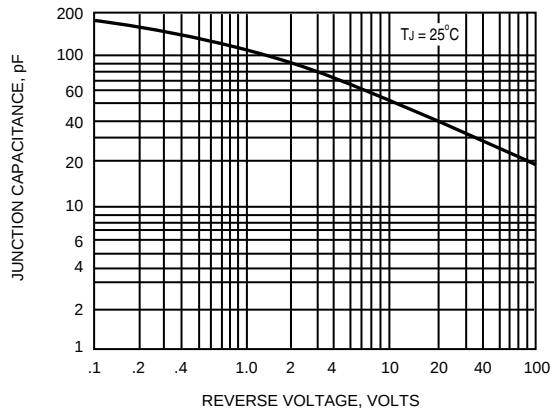


FIG.6 - TYPICAL TRANSIENT THERMAL IMPEDANCE

